



Dec. 3, 2007

To: Commissioner for Patents  
 P.O. Box 1450  
 Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761  
 28 Davis Avenue  
 Poughkeepsie, N.Y. 12603

Subject:

Serial No.	10/796,427	03/09/04
MOU-SHIUNG LIN		
“WIREBOND PAD FOR SEMICONDUCTOR CHIP OR WAFER”		
Grp. Art Unit: 2822	LEWIS, MONICA	

## RESPONSE TO NON-FINAL OFFICE ACTION

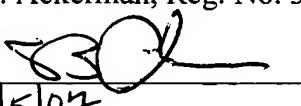
Dear Sir:

In response to the Non-Final Office Action mailed Aug. 24, 2007, please amend the above-identified application for patent and consider the remarks as follows:

## CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on Dec. 5, 2007.

Stephen B. Ackerman, Reg. No. 37,761

Signature Date 12/5/07

Amendments to the Claims begin on page 3 of this paper.

Remarks/Arguments begin on page 10 of this paper.